

A2  
--Modification to the TFI, see U.S. patent 5,207,585, issued May 4, 1993, to Byrnes et al., for Thin Interface Pellicle for Dense Arrays of Electrical Interconnects, the entire contents of the disclosure of which is hereby incorporated by reference, process to introduce the paired short may be relatively simple and can be implemented in several ways. The short metallurgy can be on either side of the probe bumps. Figs. 5a, 5b, 5c, and 5d depict process steps that may be utilized in forming a standard thin film interface. These process steps may be utilized to form a thin film interface structure according to the present invention as well, although with modifications.--

IN THE CLAIMS

Please cancel claims 1 through 13 without prejudice.

REMARKS

Claims 14 through 29 remain pending in this divisional application.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to IBM Deposit Account No. 09-0456 for any additional fees required, and the Commissioner is authorized to charge CBLH Deposit Account No. 22-0185 for extension of time fees.

Respectfully submitted,

*Larry J. Hume*

Larry J. Hume, Reg. No. 44,163  
Connolly Bove Lodge & Hutz LLP  
1990 M Street, N.W., Suite 800  
Washington, D.C. 20036-3425  
Telephone: 202-331-7111